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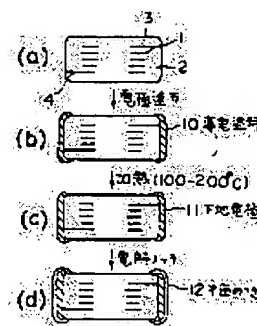
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(54) LOW-TEMPERATURE CONSTITUTION OF CHIP-COMPONENT TERMINAL

(57)Abstract:

PURPOSE: To prevent an electrolyte from being captured when a bore is formed, to prevent a characteristic from being lowered by this and to increase a bonding strength by a method wherein, for a substratum electrode, a metal powder is mixed and dispersed in an epoxy resin, a phenolic resin or other resins and this mixture is thermally hardened at 350°C or lower.

CONSTITUTION: An Ni-Cu-Zn-based ferrite layer and an Ag-Pd conductor are laminated and printed alternately by a lamination method; both side-faces of a sintered chip for inductor use are coated with a conductive paint 10 composed of an Ag powder/an epoxy resin; this paint is hardened at a temperature of 300°C or lower; a substratum electrode 11 is formed. Then, while N₂ gas is being blown by a well-known barrel plating method, a solder is plated 12. During this process, a plating formation is executed in an organic carboxylic acid solder bath. Thereby, a bonding strength, a solder heat-resistant property and the like can be improved.



LEGAL STATUS

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